



Product Change Notification: MAAN-22ZQNS715

Date:

25-Jun-2026

Product Category:

Memory

Notification Subject:

CCB 7789.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA32A, 24AA32AF, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS64, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC256, 24FC64, 24FC64F, 24LC32A, 24LC32AF, 24LC64, 24LC64F, AT24C32 and AT24C32E device families available in 5L SOT-23 package at MTAI assembly site.

Affected CPNs:

[MAAN-22ZQNS715_Affected_CPN_06252026.pdf](#)

[MAAN-22ZQNS715_Affected_CPN_06252026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA32A, 24AA32AF, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS64, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC256, 24FC64, 24FC64F, 24LC32A, 24LC32AF, 24LC64, 24LC64F, AT24C32 and AT24C32E device families available in 5L SOT-23 package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS Free)	8390A (PFAS Free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 23 September 2026 (date code: 2639)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	September 2026				
Work Week	23	24	25	26	27		36	37	38	39	40
Qual Report Availability				x							
Final PCN Issue Date				x							
Estimated Implementation Date										x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 25, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_MAAN-22ZQNS715_Qual Report.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [**PCN home page**](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [**PCN FAQ**](#) section.

If you wish to change your PCN profile, including opt out, please go to the [**PCN home page**](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

24AA32AFT-I/OT

24AA32AT-I/OT

24AA64FT-I/OT

24AA64T-E/OT

24AA64T-I/OT

24AA64T-I/OTCODTW

24CS128T-E/OT

24CS128T-I/OT

24CS256T-E/OT

24CS256T-I/OT

24CS32T-E/OT

24CS32T-I/OT

24CS64T-E/OT

24CS64T-I/OT

24CW1280T-I/OT

24CW160T-I/OT

24CW320T-I/OT

24CW640T-I/OT

24FC256T-E/OT

24FC256T-I/OT

24FC64FT-I/OT

24FC64T-I/OT

24LC32AFT-E/OT

24LC32AFT-I/OT

24LC32AT-E/OT

24LC32AT-I/OT

24LC64FT-E/OT

24LC64FT-I/OT

24LC64T-E/OT

24LC64T-E/OTCODTW

24LC64T-I/OT

AT24C32D-STUM-T

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QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: MAAN-22ZQNS715

Date:
June 25, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA32A, 24AA32AF, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS64, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC256, 24FC64, 24FC64F, 24LC32A, 24LC32AF, 24LC64, 24LC64F, AT24C32 and AT24C32E device families available in 5L SOT-23 package at MTAI assembly site.



MICROCHIP Package Qualification Report

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24AA32A, 24AA32AF, 24AA64, 24AA64F, 24CS128, 24CS256, 24CS32, 24CS64, 24CW1280, 24CW160, 24CW320, 24CW640, 24FC256, 24FC64, 24FC64F, 24LC32A, 24LC32AF, 24LC64, 24LC64F, AT24C32 and AT24C32E device families available in 5L SOT-23 package at MTAI assembly site.

CCB No.: 7789 (Qual Date: May 14, 2026) and 7789.001

Misc.	Assembly site	MTAI
	BD Number	BD-003700-01
	MP Code (MPC)	66828YC7XD00
	Part Number (CPN)	24CS256T-E/OT
	Assembly Shipping Media (T/R, Tube/Tray)	T&R
	Base Quantity Multiple (BQM)	3000
Lead-Frame	Paddle size	66 x 48 mils
	Material	CDA194
	DAP Surface Prep	Ag spot
	Treatment	Roughened
	Process	Stamped
	Lead-lock	No
	Part Number	10100503
	Lead Plating	Matte tin
	Strip Size	229 x 51 mm
Bond Wire	Strip Density	x192
	Material	CuPdAu
Die Attach	Part Number	8390A
	Conductive	Yes
MC	Part Number	G600V
PKG	PKG Type	SOT-23
	Pin/Ball Count	5
	PKG width/size	2.7 x 1.3 mm



MICROCHIP

Package Qualification Report

Manufacturing Information:

Assembly Lot No.	Package
MTAI264301131.000	5L SOT-23
MTAI264301941.000	5L SOT-23
MTAI264301941.000	5L SOT-23

Conclusion:

Qualification of 66828 mask / 24CS256T-E/OT product / 0.8 mil CuPdAu wire in 5L SOT-23 2.7x1.3 mm package at MTAI site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2600135-1 MTAI264301131.000	R2600135-2 MTAI264301941.000	R2600135-2 MTAI264301942.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: NEXTEST_PT	25°C, 85°C and 125°C		
Result	Passed		



MICROCHIP Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 3 lot;		
Lot ID	R2600135-1 MTAI264301131.000	R2600135-2 MTAI264301941.000	R2600135-2 MTAI264301942.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: NEXTEST_PT	25°C, 85°C and 125°C		
Result	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600135-1 MTAI264301131.000	R2600135-2 MTAI264301941.000	R2600135-2 MTAI264301942.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: NEXTEST_PT	85°C and 125°C		
Result	Passed		



MICROCHIP Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.0 V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600135-1 MTAI264301131.000	R2600135-2 MTAI264301941.000	R2600135-2 MTAI264301942.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: NEXTEST_PT	25°C, 85°C and 125°C		
Result	Passed		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600135-1 MTAI264301131.000	R2600135-2 MTAI264301941.000	R2600135-2 MTAI264301942.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: NEXTEST_PT	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result	Passed



MICROCHIP

Package Qualification Report

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 215°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result	Passed

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed

Bond Line Thickness

Test Method	SPI-45528
Test Criteria	0.60-1.50mils
Required Sample Size	5 units each lot / 3 lots
Result (Fail / Pass)	0/15
Result	Passed